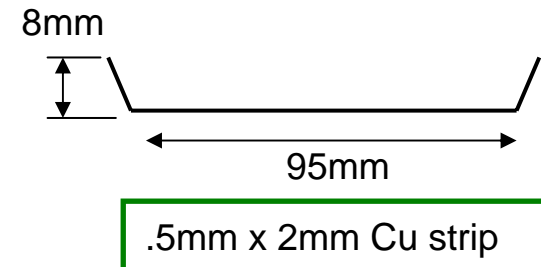
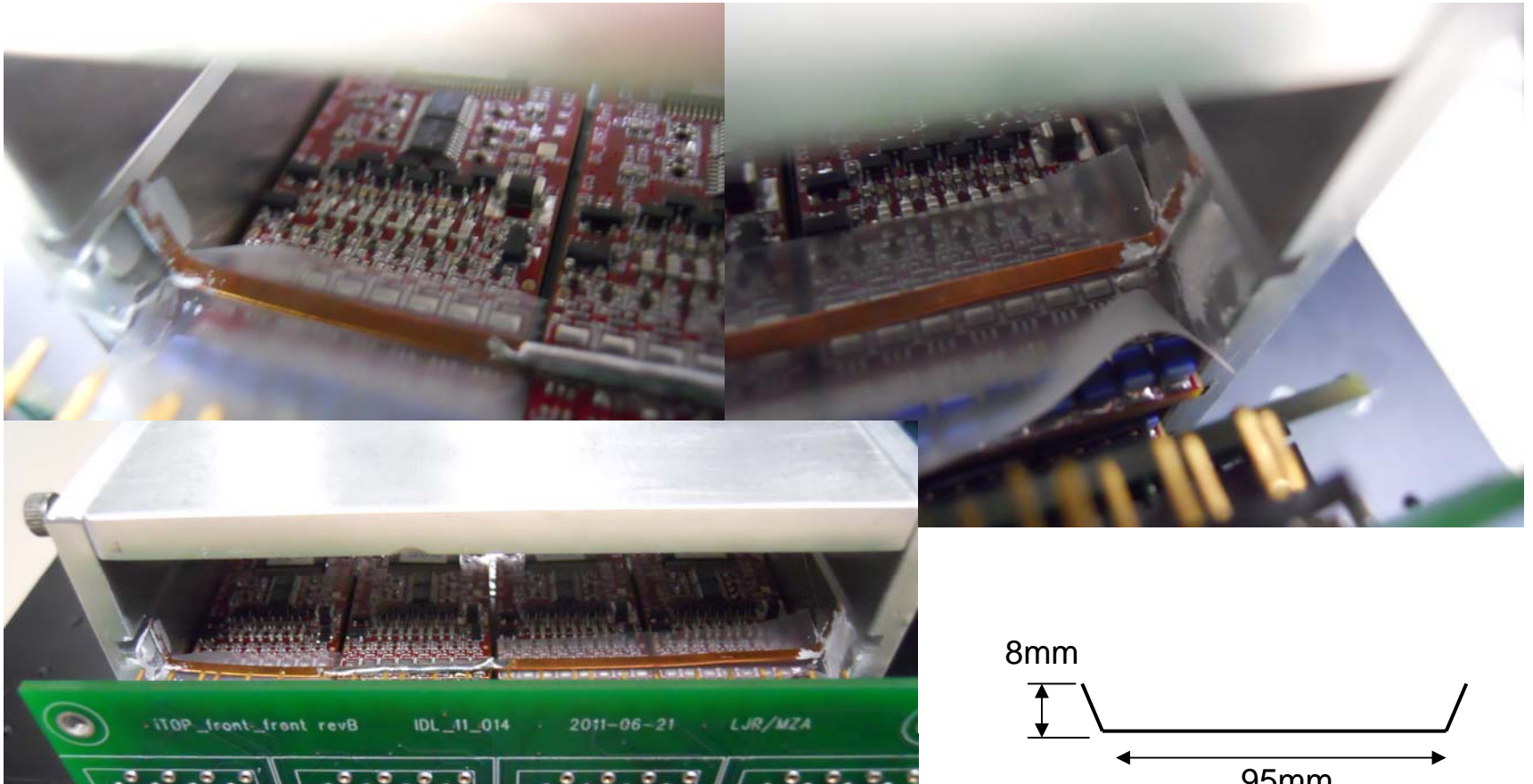
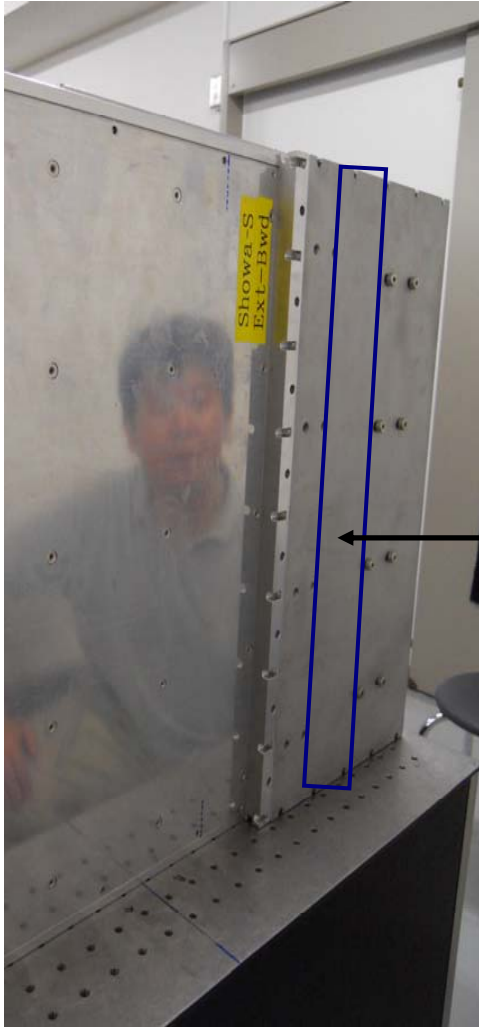


Thermal mitigation, step 1: heat strap the hot spots on the daughter cards to the sidewalls of the card cage structure.



Thermal mitigation, step 2: mount the Nagoya Cu cooling plates to the upper and lower surfaces of the external housing.



The Nagoya cooling plates will be cut down by 3-4mm and new threaded holes will be made in the in the large plates of the external electronics enclosure.